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(71)Applicant : FUJITSU LTD

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(72)Inventor : OTAKE FUMIO

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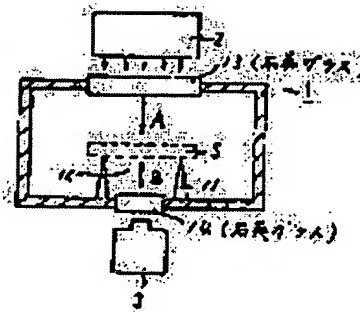
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### (54) MANUFACTURING DEVICE FOR SEMICONDUCTOR DEVICE

(57)Abstract:

**PURPOSE:** To contrive improvement in the accuracy of measurement by a method wherein a radiant light of heating is made to radiate a substrate via a filter which does not transmit the range of wavelength which is sensed by a radiant light detecting means, and the radiant light only coming from a substrate itself is detected.

**CONSTITUTION:** Among the radiant lights to be radiated from a heating radiant light radiating means 2, only the radiant light in the range of transmission wavelength of the initial filter 13 passes the filter 13. Accordingly, the range of wavelength of 2600 to 2900nm is removed from the radiant light A passed through the filter 13. A substrate 5 is heated up



*by this radiant light A. The radiant light having a wide range of wavelength is radiated from the high temperature substrate 5. The radiant light B, which is the sum of the above- mentioned radiant lights, is made incident on a radiant light detection filter 14. As the radiant light detection filter 14 transmits the wavelength of the prescribed range, the radiant light only of the high temperature substrate 5 itself is measured by measuring it with the radiant light detection means 3 having the sensitivity of the prescribed range, and the substrate temperature can be measured in a highly precise manner.*

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#### **LEGAL STATUS**

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